

Features

Type	V _{DSS}	R _{DS(on)}	I _D
STS4DNF60L	60V	<0.055Ω	4A

- Standard outline for easy automated surface mount assembly
- Low threshold drive

Application

- Switching applications

Description

This Power MOSFET is the latest development of STMicroelectronics unique “single feature size” strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

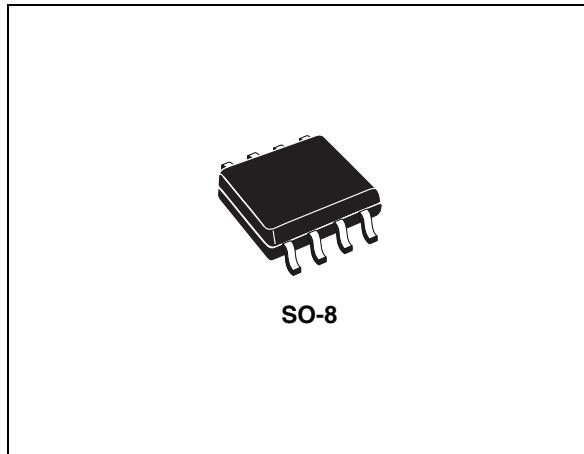


Figure 1. Internal schematic diagram

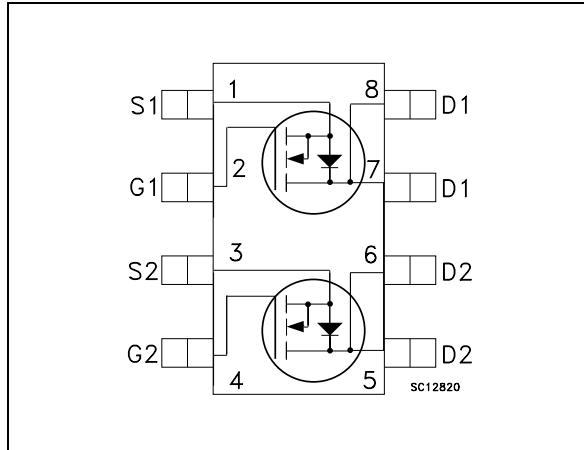


Table 1. Device summary

Order code	Marking	Package	Packaging
STS4DNF60L	4DF60L	SO-8	Tape & reel

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves)	6
3	Test circuits	8
4	Package mechanical data	9
5	Revision history	11

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	60	V
V_{GS}	Gate- source voltage	± 15	V
I_D	Drain current (continuous) at $T_C = 25^\circ C$	4	A
I_D	Drain current (continuous) at $T_C = 100^\circ C$	2.5	A
$I_{DM}^{(1)}$	Drain current (pulsed)	16	A
$P_{TOT}^{(2)}$	Total dissipation at $T_C = 25^\circ C$	2	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	80	mJ
T_j T_{stg}	Operating junction temperature Storage temperature	- 55 to 150	$^\circ C$

- 1. Pulse width limited by safe operating area
- 2. $P_{TOT}=1.6$ W for single operation
- 3. Starting $T_J = 25^\circ C$, $I_D = 4$ A, $V_{DD} = 30$ V

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-pcb}$	Thermal resistance junction-pcb D.O. ⁽¹⁾	62.5	$^\circ C/W$

- 1. When mounted on inch² FR-4 board, 2 Oz Cu, $t \leq 10$ sec, dual operation

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0$	60			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}, T_C = 125^\circ\text{C}$			1 10	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 15 \text{ V}$			± 100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1	1.7	2.5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 2 \text{ A}$		0.045 0.050	0.055 0.065	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}, I_D = 2 \text{ A}$	-	25	-	S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	1030 140 40	-	pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 48 \text{ V}, I_D = 4 \text{ A},$ $V_{GS} = 4.5 \text{ V}$ (see Figure 13)	-	15 4 4	-	nC nC nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	$V_{DD} = 30 \text{ V}$, $I_D = 2.2 \text{ A}$, $R_G = 4.7 \Omega$, $V_{GS} = 10 \text{ V}$	-	15 28	-	ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	(see Figure 12)	-	45 10	-	ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)		-		4 16	A A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 4 \text{ A}$, $V_{GS} = 0$	-		1.2	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 4 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 20 \text{ V}$ (see Figure 17)	-	85 85 2		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

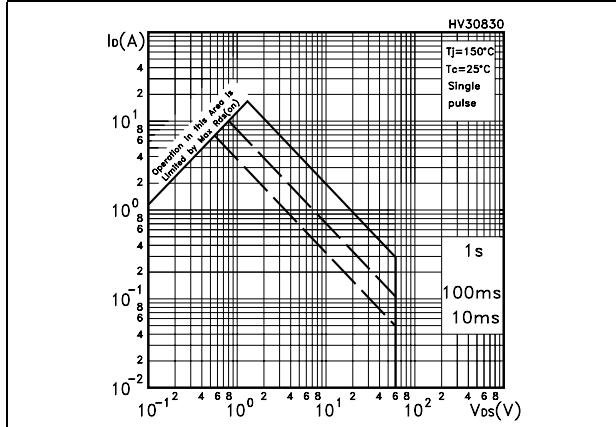


Figure 3. Thermal impedance

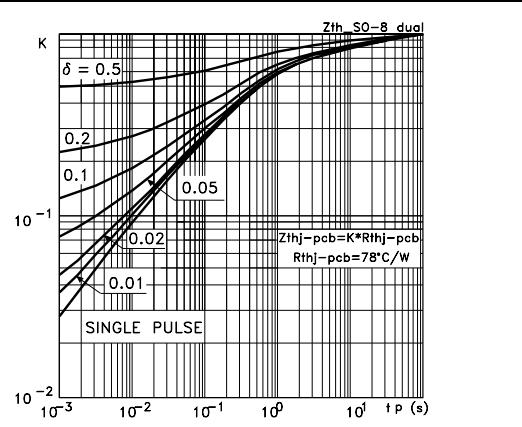


Figure 4. Output characteristics

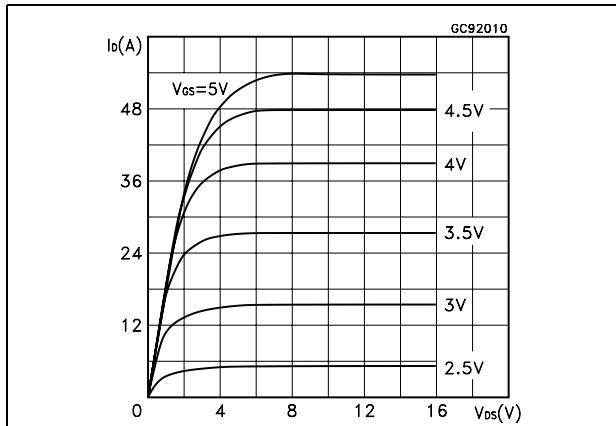


Figure 5. Transfer characteristics

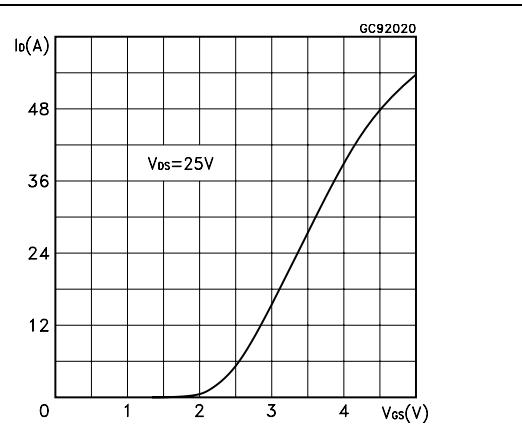


Figure 6. Source-drain diode forward characteristics

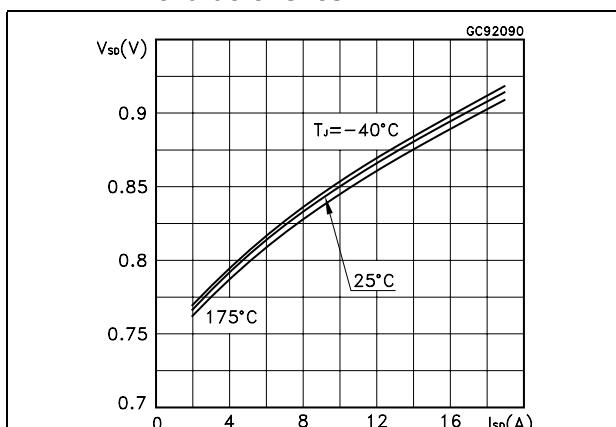


Figure 7. Static drain-source on resistance

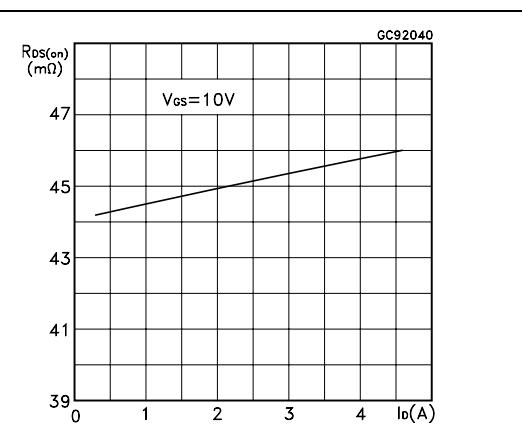
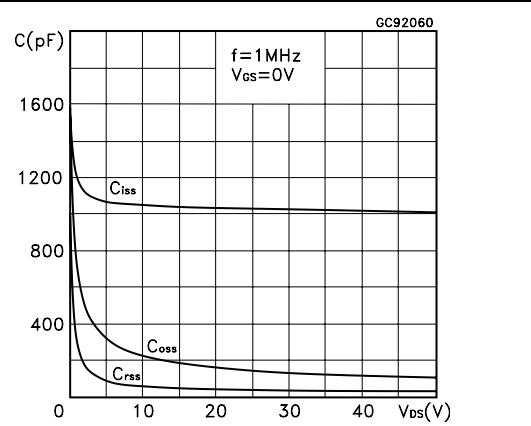
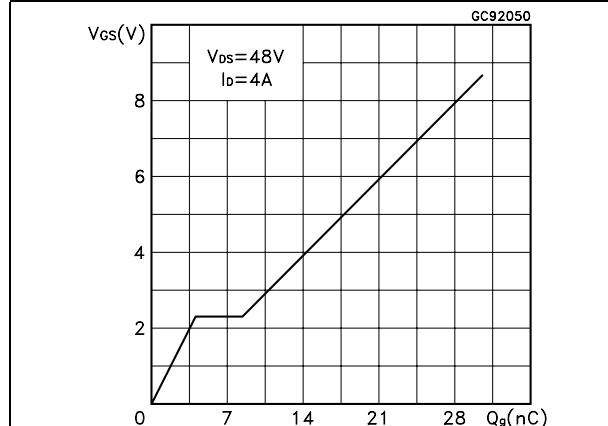
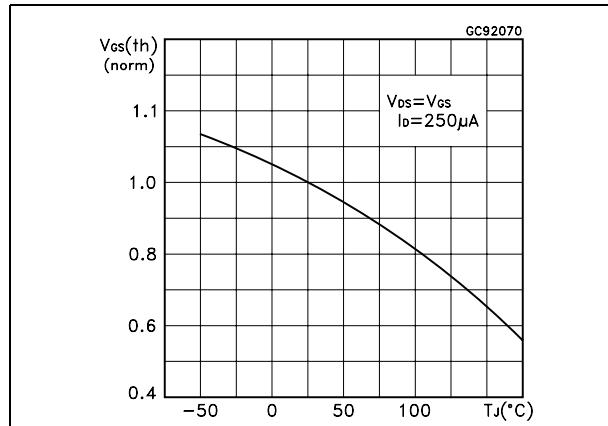
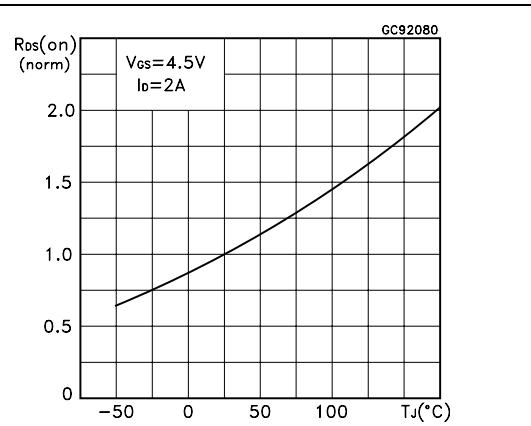


Figure 8. Gate charge vs gate-source voltage**Figure 10. Normalized gate threshold voltage vs temperature****Figure 11. Normalized on resistance vs temperature**

3 Test circuits

Figure 12. Switching times test circuit for resistive load

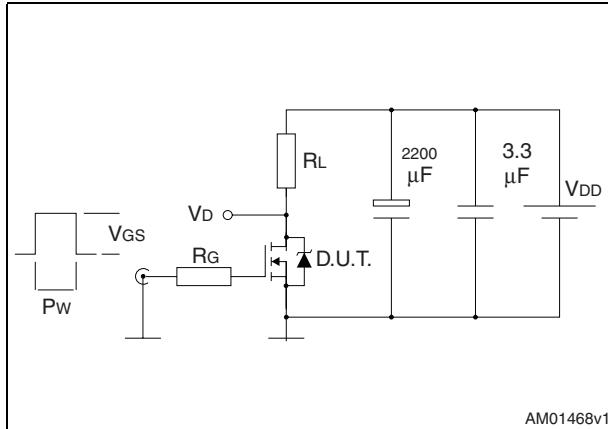


Figure 13. Gate charge test circuit

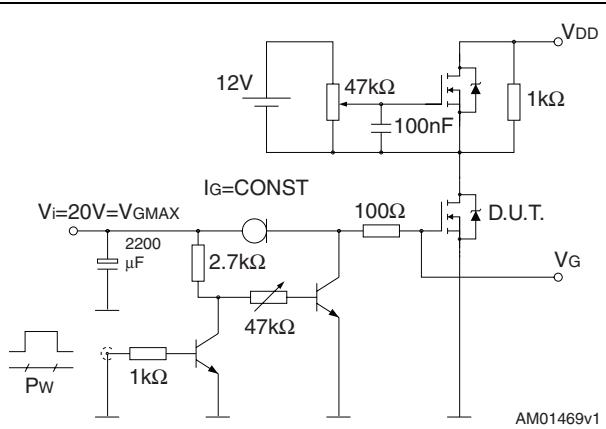


Figure 14. Test circuit for inductive load switching and diode recovery times

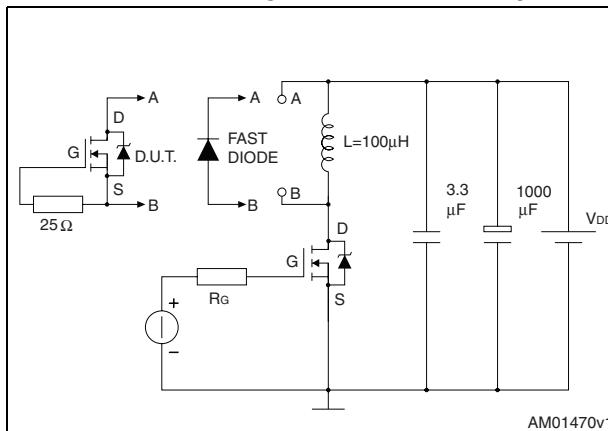


Figure 15. Unclamped Inductive load test circuit

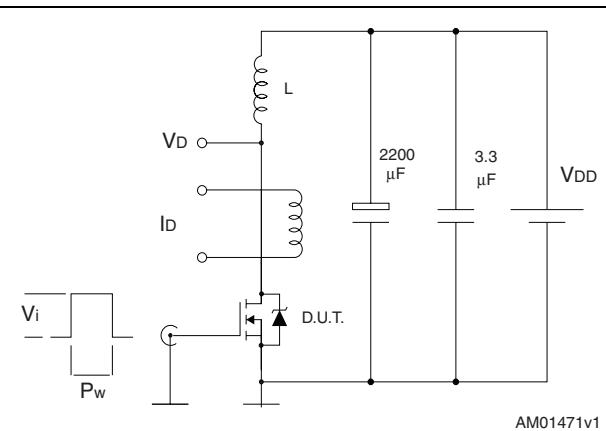


Figure 16. Unclamped inductive waveform

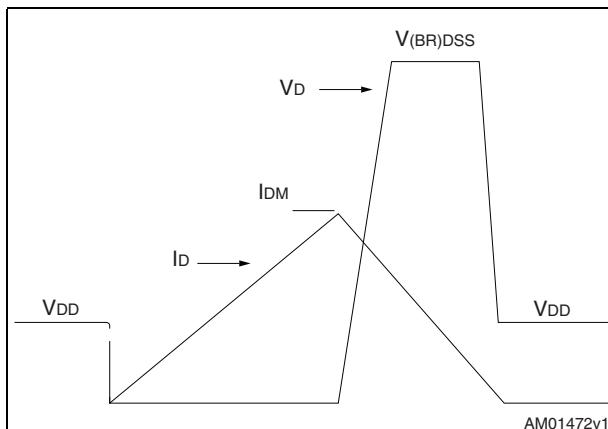
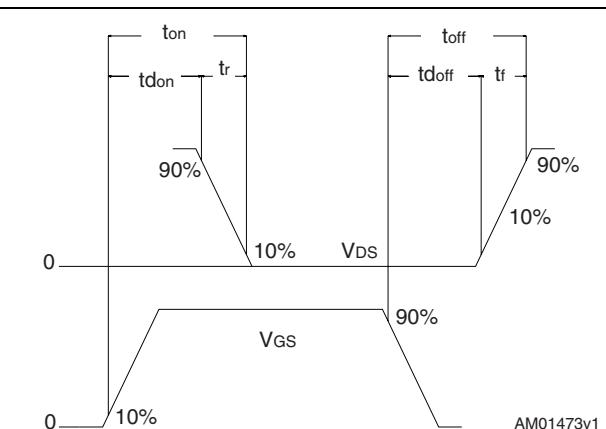


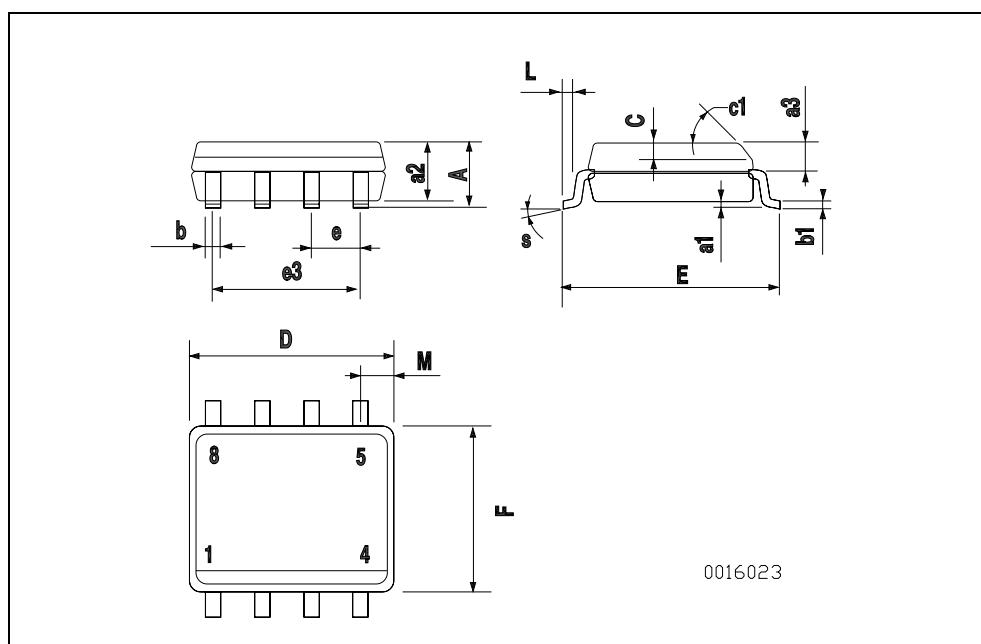
Figure 17. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

SO-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a ₁	0.1		0.25	0.003		0.009
a ₂			1.65			0.064
a ₃	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b ₁	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c ₁			45 (typ.)			
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e ₃		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S			8 (max.)			



5 Revision history

Table 8. Document revision history

Date	Revision	Changes
30-May-2005	5	Initial electronic version
29-Mar-2006	6	Modified Figure 2 and Figure 3
16-May-2006	7	Modified internal schematic diagram
29-Aug-2007	8	Marking has been updated
30-Mar-2010	9	Inserted E_{AS} value in Table 2: Absolute maximum ratings

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